EQUIPMENT CARD

PLAPIQUI



5608

Vacuum furnaces (Cole Parmer)

DESCRIPTION

Drying ovens that operate under reduced pressure. Lowering the pressure lowers the boiling point of the solvent, so the sample dries at a lower temperature and in less time, without thermal degradation or oxidation.

MAIN FEATURES

- Principle: drying under reduced pressure, with an external vacuum pump
- Chamber: stainless steel interior, with removable shelves and viewing door
- Heating: heating elements in the chamber walls, with digital temperature control
- Temperature range: from ambient up to the maximum of each model (usually 200-250 °C)
- Vacuum: gauge and inert gas inlet valves to purge or release the vacuum
- Safety: independent over-temperature control

MAIN APPLICATIONS

- Drying of catalysts and supports without altering their pore structure
- Removal of residual solvents from synthesis products
- Sample conditioning prior to textural or elemental analysis
- Drying of thermolabile extracts and natural products
- Moisture determination in temperature-sensitive solids

ASSOCIATED TECHNOLOGY, SERVICE AND CAPABILITY

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